



4-20mA Current-Loop Transmitter

FEATURES

- LOW QUIESCENT CURRENT: 130 μ A
- 5V REGULATOR FOR EXTERNAL CIRCUITS
- LOW SPAN ERROR: 0.05%
- LOW NONLINEARITY ERROR: 0.003%
- WIDE-LOOP SUPPLY RANGE: 7.5V to 40V
- MSOP-8 PACKAGE

APPLICATIONS

- 2-WIRE, 4-20mA CURRENT LOOP TRANSMITTER
- SMART TRANSMITTER
- INDUSTRIAL PROCESS CONTROL
- TEST SYSTEMS
- CURRENT AMPLIFIER
- VOLTAGE-TO-CURRENT AMPLIFIER

DESCRIPTION

The XTR117 is a precision current output converter designed to transmit analog 4-20mA signals over an industry-standard current loop. It provides accurate current scaling and output current limit functions.

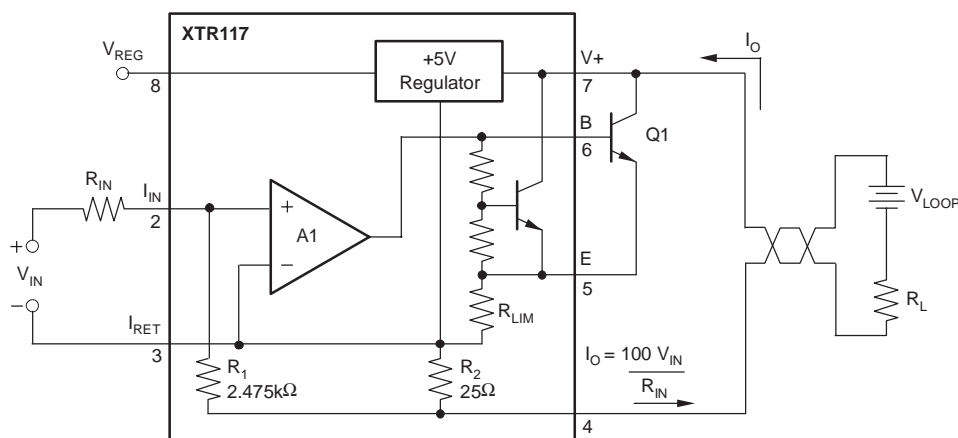
The on-chip voltage regulator (5V) can be used to power external circuitry. A current return pin (I_{RET}) senses any current used in external circuitry to assure an accurate control of the output current.

The XTR117 is a fundamental building block of smart sensors using 4-20mA current transmission. The XTR117 is specified for operation over the extended industrial temperature range, -40°C to $+125^{\circ}\text{C}$.

RELATED 4-20mA PRODUCTS

XTR115	5V regulator output and 2.5V reference output
XTR116	5V regulator output and 4.096V reference output

NOTE: For 4-20mA complete bridge and RTO conditioner solutions, see the XTR product family at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Power Supply, V ₊ (referenced to I _O pin)	+50V
Input Voltage, (referenced to I _{RET} pin)	0V to V ₊
Output Current Limit	Continuous
V _{REG} , Short-Circuit	Continuous
Operating Temperature Range	–55°C to +125°C
Storage Temperature Range	–55°C to +125°C
Junction Temperature	+165°C
ESD Rating (Human Body Model)	2000V
(Charged Device Model)	1000V

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

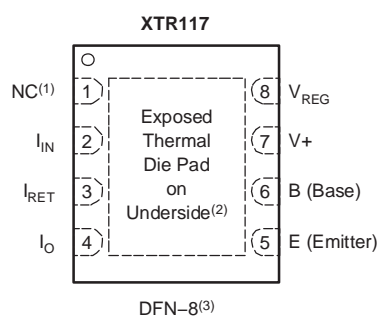
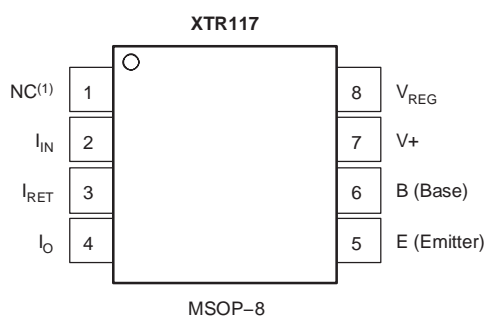
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
XTR117	MSOP-8	DGK	BOZ	XTR117AIDGKT	Tape and Reel, 250
				XTR117AIDGKR	Tape and Reel, 2500
XTR117 ⁽²⁾	DFN-8	DRB	BOY	XTR117AIDRBT	Tape and Reel, 250
				XTR117AIDRBR	Tape and Reel, 3000

(1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

(2) Available Q1 2006.

PIN ASSIGNMENTS**Top View**

NOTES: (1) NC = No connection. Leave unconnected on PCB.
 (2) Connect thermal die pad to V_–.
 (3) Available Q1 2006.

ELECTRICAL CHARACTERISTICS: V₊ = +24V

Boldface limits apply over the temperature range, T_A = –40°C to +125°C.

All specifications at T_A = +25°C, V₊ = 24V, R_{IN} = 20kΩ, and TIP29C external transistor, unless otherwise noted.

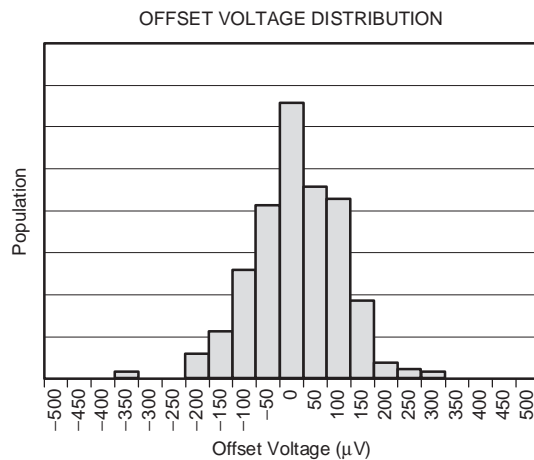
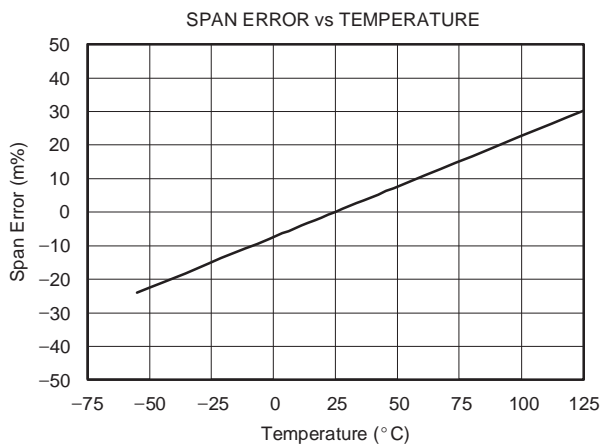
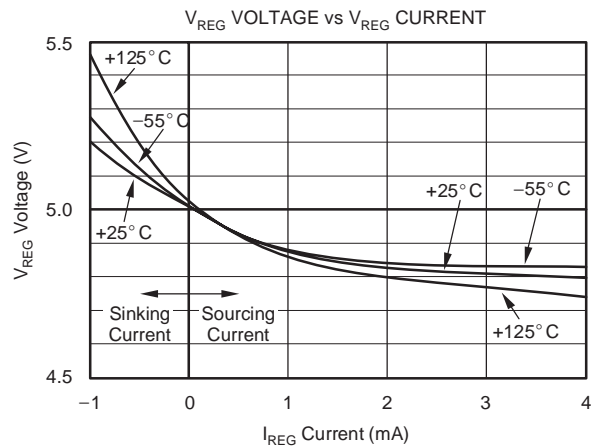
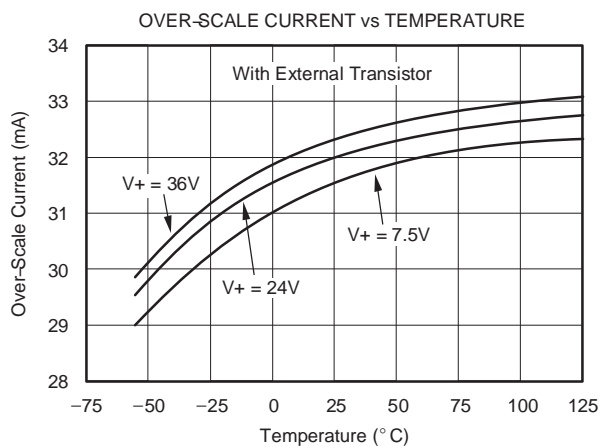
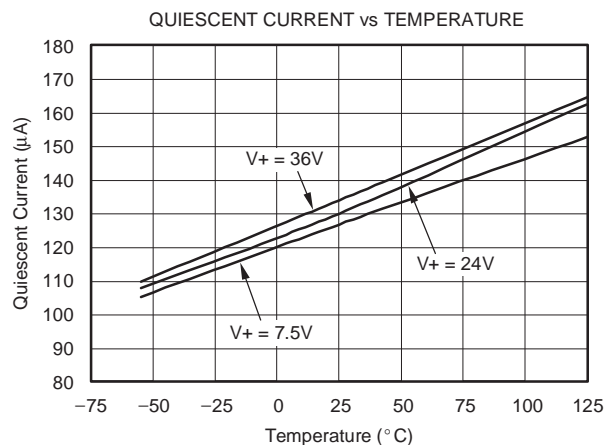
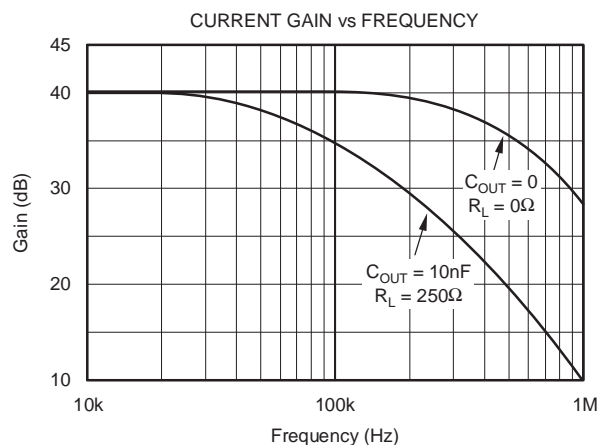
PARAMETER	CONDITION	XTR117			UNITS
		MIN	TYP	MAX	
OUTPUT					
Output Current Equation	I _O		I _O = I _{IN} × 100		
Output Current, Linear Range		0.20		25	mA
Over-Scale Limit	I _{LIM}		32		mA
Under-Scale Limit	I _{MIN}		0.13	0.20	mA
	I _{REG} = 0				
SPAN					
Span (Current Gain)	S		100		A/A
Error ⁽¹⁾			±0.05	±0.4	%
vs Temperature			±3	±20	ppm/°C
Nonlinearity			±0.003	±0.02	%
INPUT					
Offset Voltage (Op Amp)	V _{OS}		±100	±500	μV
vs Temperature			±0.7	±6	μV/°C
vs Supply Voltage, V ₊			+0.1	+2	μV/V
Bias Current	I _B		–35		nA
vs Temperature			150		pA/°C
Noise: 0.1Hz to 10Hz	e _n		0.6		μV _{PP}
DYNAMIC RESPONSE					
Small-Signal Bandwidth	C _{LOOP} = 0, R _L = 0		380		kHz
Slew Rate			3.2		mA/μs
V_{REG}⁽²⁾					
Voltage			5		V
Voltage Accuracy			±0.05	±0.1	V
vs Temperature			±0.1		mV/°C
vs Supply Voltage, V ₊			1		mV/V
vs Output Current			See Typical Characteristics		
Short-Circuit Current			12		mA
POWER SUPPLY					
Specified Voltage Range	V ₊		+24		V
Operating Voltage Range		+7.5		+40	V
Quiescent Current	I _Q		130	200	μA
Over Temperature				250	μA
	T _A = –40°C to +125°C				
TEMPERATURE RANGE					
Specified Range		–40		+125	°C
Operating Range		–55		+125	°C
Storage Range		–55		+150	°C
Thermal Resistance	θ _{JA}				
MSOP			150		°C/W
DFN			53		°C/W

(1) Does not include initial error or temperature coefficient of R_{IN}.

(2) Voltage measured with respect to I_{RET} pin.

TYPICAL CHARACTERISTICS: $V_+ = +2.7V$ to $+5.5V$

At $T_A = +25^\circ\text{C}$, $V_+ = 24V$, $R_{IN} = 20k\Omega$, and TIP29C external transistor, unless otherwise noted.



APPLICATIONS INFORMATION

BASIC OPERATION

The XTR117 is a precision current output converter designed to transmit analog 4-20mA signals over an industry-standard current loop. Figure 1 shows basic circuit connections with representative simplified input circuitry. The XTR117 is a two-wire current transmitter. Its input current (pin 2) controls the output current. A portion of the output current flows into the V+ power supply, pin 7. The remaining current flows in Q₁. External input circuitry connected to the XTR117 can be powered from V_{REG}. Current drawn from these terminals must be returned to I_{RET}, pin 3. The I_{RET} pin is a *local ground* for input circuitry driving the XTR117.

The XTR117 is a current-input device with a gain of 100. A current flowing into pin 2 produces I_O = 100 × I_{IN}. The input voltage at the I_{IN} pin is zero (referred to the I_{RET} pin). A voltage input is converted to an input current with an external input resistor, R_{IN}, as shown in Figure 1. Typical full-scale input voltages range from 1V and upward. Full-scale inputs greater than 0.5V are recommend to minimize the effects of offset voltage and drift of A1.

EXTERNAL TRANSISTOR

The external transistor, Q₁, conducts the majority of the full-scale output current. Power dissipation in this transistor can approach 0.8W with high loop voltage (40V) and 20mA output current. The XTR117 is designed to use an external transistor to avoid on-chip, thermal-induced errors. Heat produced by Q₁ will still cause ambient temperature changes that can influence the XTR117 performance. To minimize these effects, locate Q₁ away from sensitive analog circuitry, including XTR117. Mount Q₁ so that heat is conducted to the outside of the transducer housing.

The XTR117 is designed to use virtually any NPN transistor with sufficient voltage, current and power rating. Case style and thermal mounting considerations often influence the choice for any given application. Several possible choices are listed in Figure 1. A MOSFET transistor will not improve the accuracy of the XTR117 and is not recommended.

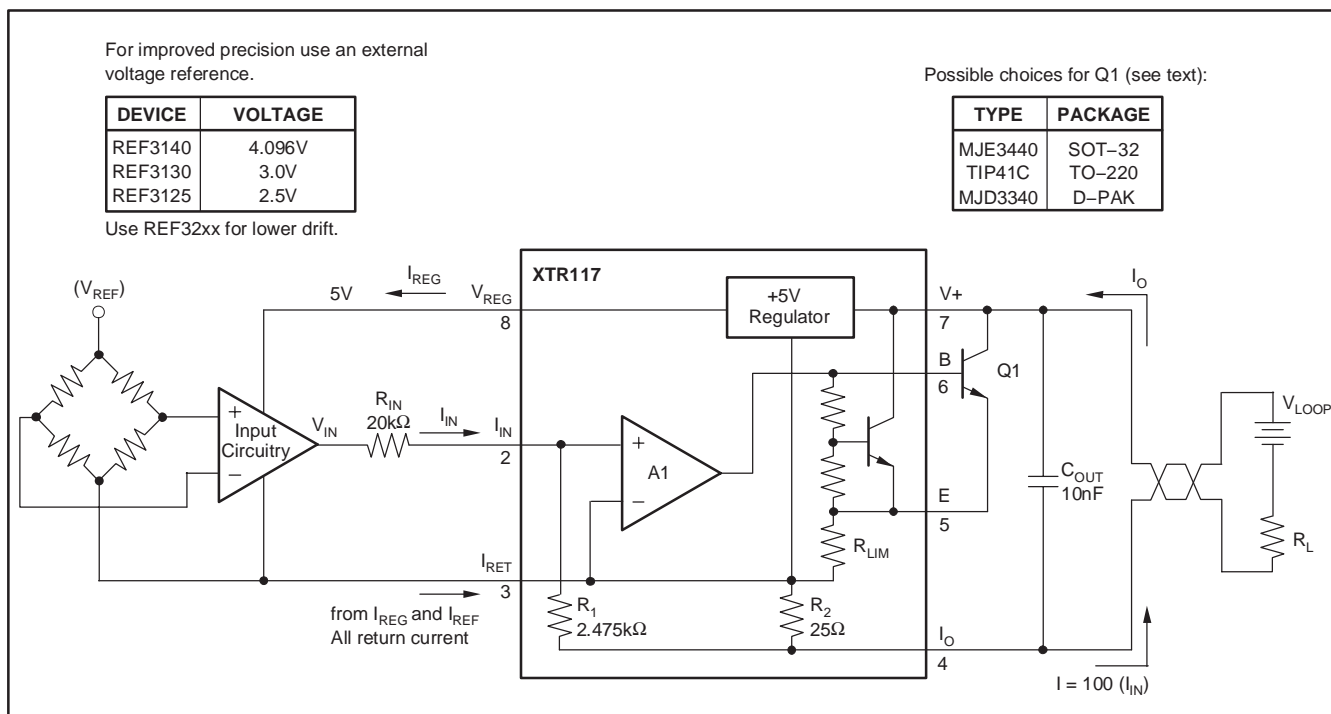


Figure 1. Basic Circuit Connections

MINIMUM OUTPUT CURRENT

The quiescent current of the XTR117 (typically 130 μ A) is the lower limit of its output current. Zero input current ($I_{IN} = 0$) will produce an I_O equal to the quiescent current. Output current will not begin to increase until $I_{IN} > I_Q/100$. Current drawn from V_{REG} will be added to this minimum output current. Up to 3.8mA is available to power external circuitry while still allowing the output current to go below 4mA.

OFFSETTING THE INPUT

A low-scale output of 4mA is produced by creating a 40 μ A input current. This input current can be created with the proper value resistor from an external reference voltage (V_{REF}) as shown in Figure 2. V_{REG} can be used as shown in Figure 2 but will not have the temperature stability of a high quality reference such as the REF3125.

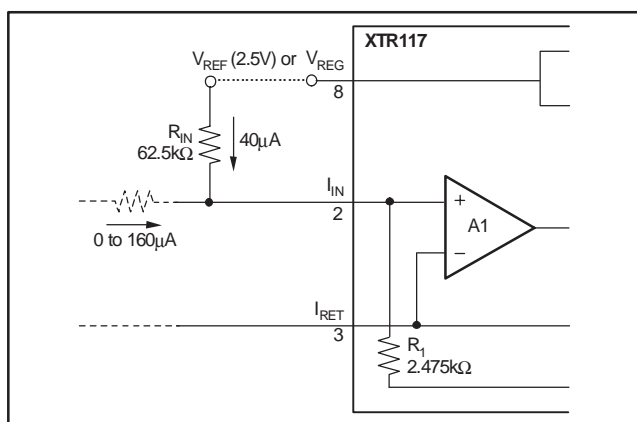


Figure 2. Creating Low-Scale Offset

MAXIMUM OUTPUT CURRENT

The XTR117 provides accurate, linear output up to 25mA. Internal circuitry limits the output current to approximately 32mA to protect the transmitter and loop power/measurement circuitry.

It is possible to extend the output current range of the XTR117 by connecting an external resistor from pin 3 to pin 5, to change the current limit value. Since all output current must flow through internal resistors, it is possible to cause internal damage with excessive current. Output currents greater than 45mA may cause permanent damage.

REVERSE-VOLTAGE PROTECTION

The XTR117 low compliance voltage rating (minimum operating voltage) of 7.5V permits the use of various voltage protection methods without compromising operating range. Figure 3 shows a diode bridge circuit which allows normal operation even when the voltage connection lines are reversed. The bridge causes a two diode drop (approximately 1.4V) loss in loop supply voltage. This voltage drop results in a compliance voltage of approximately 9V—satisfactory for most applications. A diode can be inserted in series with the loop supply voltage and the V+ pin to protect against reverse output connection lines with only a 0.7V loss in loop supply voltage.

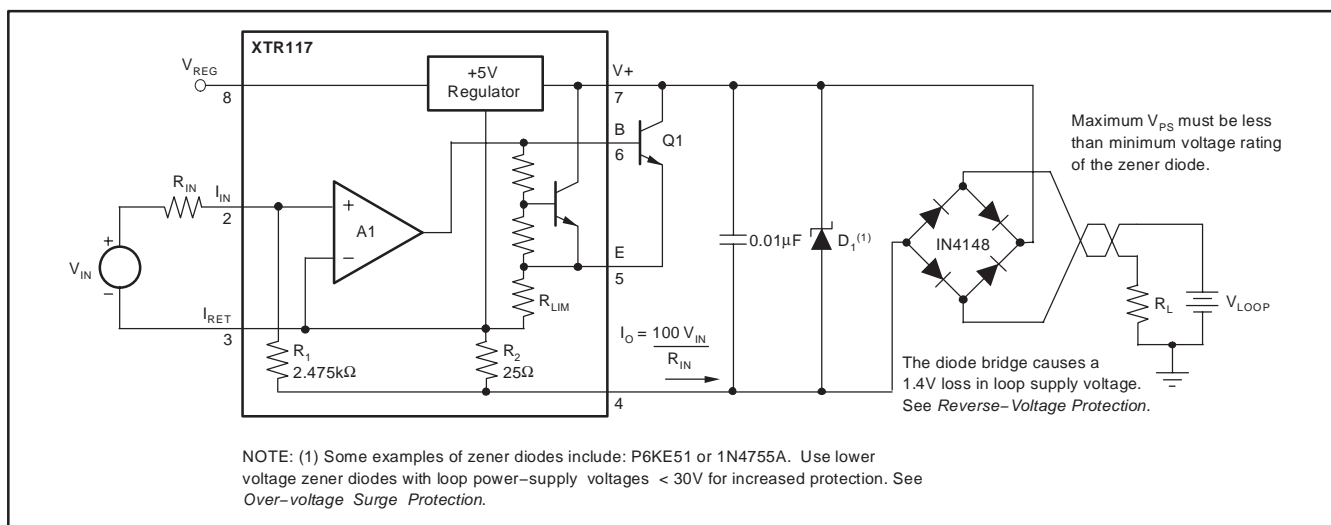


Figure 3. Reverse Voltage Operation and Over-Voltage Surge Protection

OVER-VOLTAGE SURGE PROTECTION

Remote connections to current transmitters can sometimes be subjected to voltage surges. It is prudent to limit the maximum surge voltage applied to the XTR117 to as low as practical. Various zener diode and surge clamping diodes are specially designed for this purpose. Select a clamp diode with as low a voltage rating as possible for best protection. Absolute maximum power-supply rating on the XTR117 is specified at +50V. Keep overvoltages and transients below +50V to ensure reliable operation when the supply returns to normal (7.5V to 40V).

Most surge protection zener diodes have a diode characteristic in the forward direction that will conduct excessive current, possibly damaging receiving-side circuitry if the loop connections are reversed. If a surge

protection diode is used, a series diode or diode bridge should be used for protection against reversed connections.

RADIO FREQUENCY INTERFERENCE

The long wire lengths of current loops invite radio frequency (RF) interference. RF interference can be rectified by the input circuitry of the XTR117 or preceding circuitry. This effect generally appears as an unstable output current that varies with the position of loop supply or input wiring. Interference may also enter at the input terminals. For integrated transmitter assemblies with short connections to the sensor, the interference more likely comes from the current loop connections.

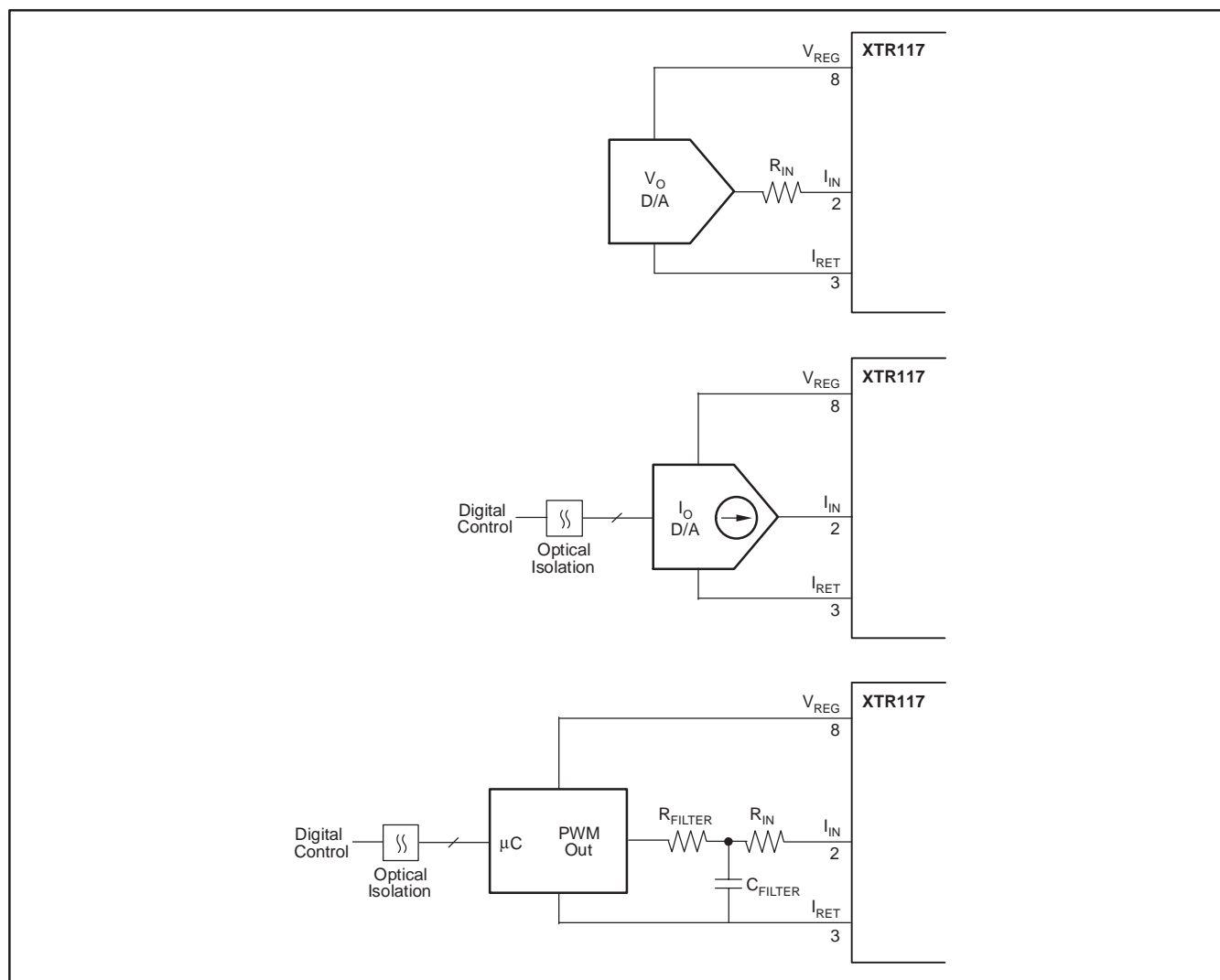


Figure 4. Digital Control Methods

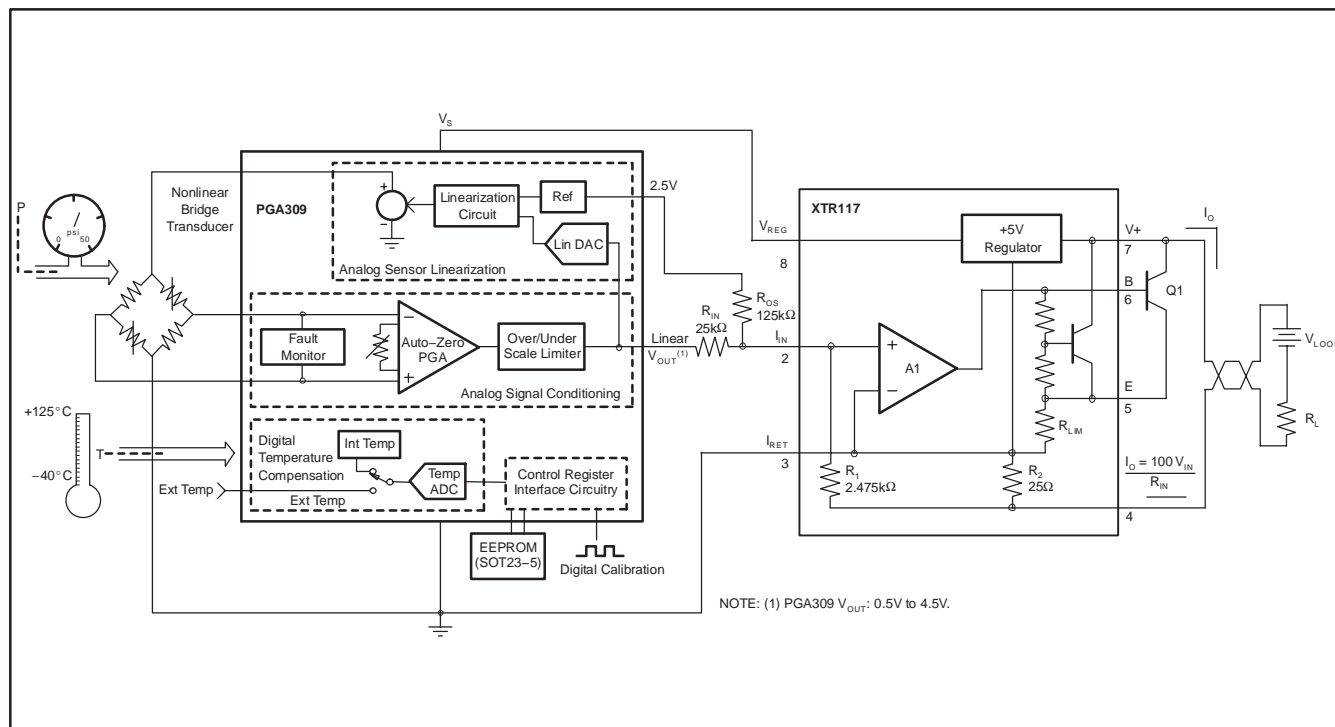


Figure 5. Complete 4-20mA Pressure Transducer Solution with PGA309 and XTR117

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
XTR117AIDGKR	ACTIVE	MSOP	DGK	8	2500	TBD	Call TI	Call TI
XTR117AIDGKT	ACTIVE	MSOP	DGK	8	250	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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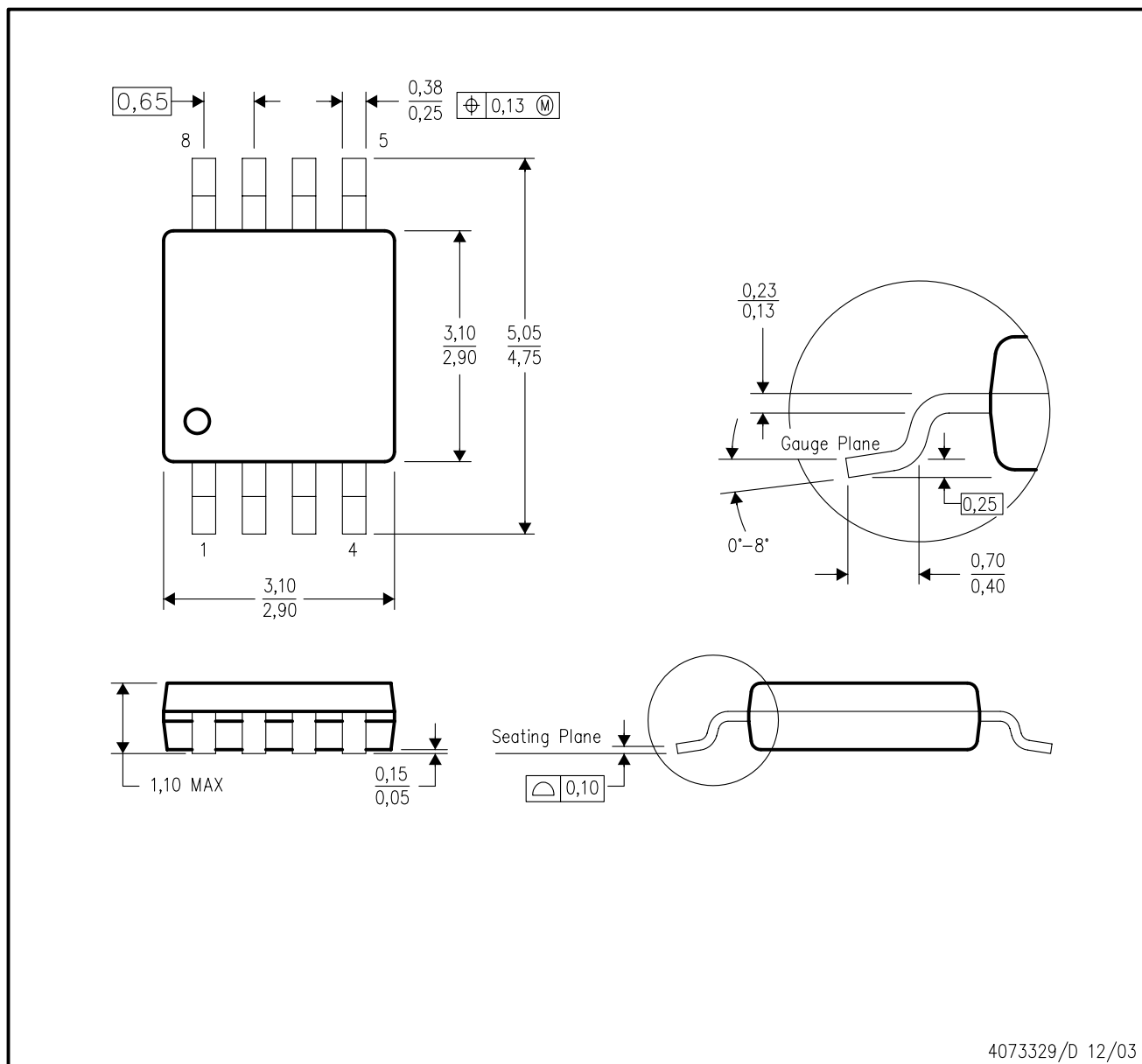
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion.
 - D. Falls within JEDEC MO-187 variation AA.

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